SK 50 B 06 UF



SEMITOP® 2

Bridge Rectifier

SK 50 B 06 UF

Target Data

Features

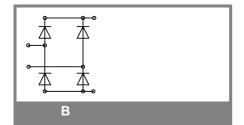
- Compact design
- · One screw mounting
- Heat transfer and insulation through direct copper bonded aluminium oxide ceramic (DCB)
- Ultra Fast diodes
- UL recognized, file no. E 63 532

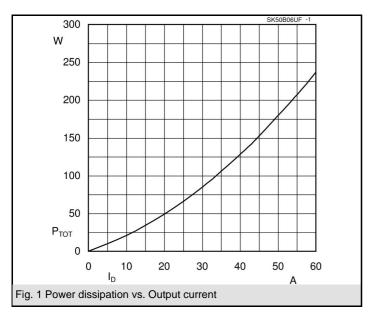
Typical Applications

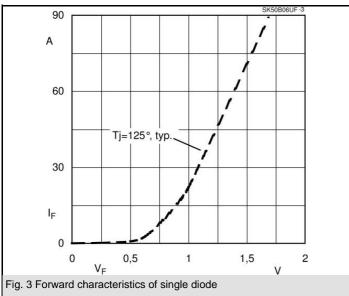
- General power switching applications
- UPS
- SMPS
- Welding equipment

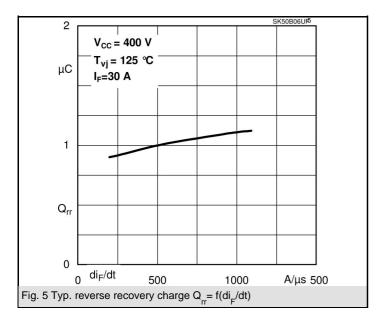
V _{RSM}	V _{RRM} , V _{DRM}	$I_D = 46 \text{ A (full conduction)}$
V	V	$(T_S = 80 \text{ °C)}$
600	600	

Symbol	Conditions	Values	Units
I _D	T _s = 80 °C	46	Α
I _{RRM}	T _{vj} =125°C;V _R =400V;I _F =30A;	11	Α
Q_{rr}	- dI _F /dt=300A/μs	typ. 0,93	μC
I _R	T _{vj} = 25 (150)°C; V _R =V _{RRM}	max 0,015 (0,475)	mA
I _{FSM}	T _{vj} = 150 °C; 10 ms	400	Α
	T _{vi} = °C; ms		Α
i²t	$T_{vj} = 150 ^{\circ}\text{C}; 10 \text{ms}$	800	A²s
	$T_{vj} = {}^{\circ}C; ms$		A²s
V _F	T _{vi} = 125 °C; I _F = 50 A	max. 1,95	V
V _(TO)	T _{vi} = 125 °C	max. 0,8	V
r _T	T _{vi} = 125 °C	max. 11	$m\Omega$
I_{RD}	$T_{vi} = {^{\circ}C}; V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$		mA
			mA
R _{th(j-s)}	per diode	1,8	K/W
ti (j-3)	per module	0,45	K/W
_	to order to 40 a	000	
T _{solder}	terminals, 10s	260	°C
T _{vj}		-40+150	
T _{stg}		-40+125	°C
V _{isol}	a. c. 50 Hz; r.m.s.; 1 s / 1 min.	3000 (2500)	V
M _s	mounting torque to heatsink	2	Nm
M_t			
m	approx. weight	19	g
Case	SEMITOP® 2	Т 6	

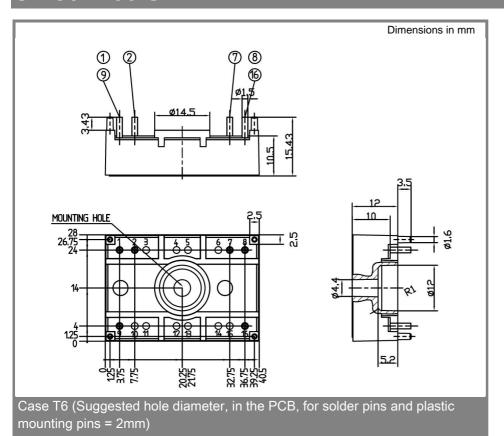


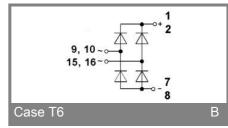






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